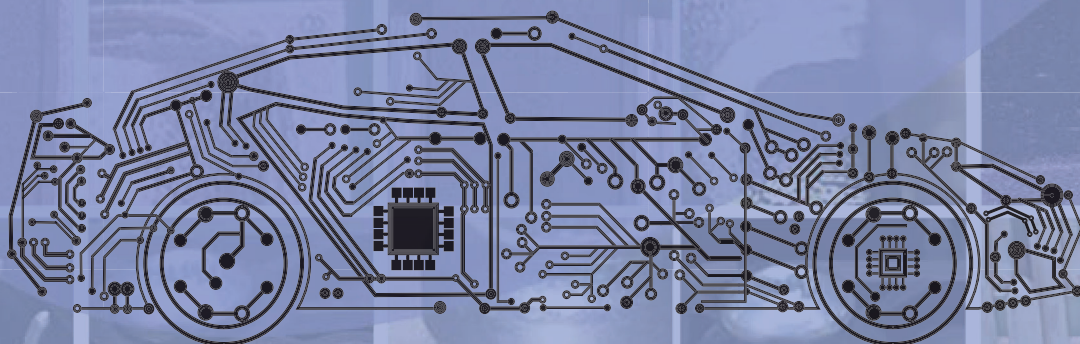


IPC J-STD-001HA/IPC-A-610HA

October 2021

**Automotive Addendum to IPC J-STD-001H
Requirements for Soldered Electrical and
Electronic Assemblies and IPC-A-610H
Acceptability of Electronic Assemblies**



Developed by



BUILD ELECTRONICS BETTER

participants from

16 countries

contributed to this standard



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